MC74VHC74

Dual D-Type Flip-Flop with Set and Reset

The MC74VHC74 is an advanced high speed CMOS D−type flip−flop fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining CMOS low power dissipation.

The signal level applied to the D input is transferred to Q output during the positive going transition of the Clock pulse.

Reset ($\overline{RD}$) and Set ($\overline{SD}$) are independent of the Clock (CP) and are accomplished by setting the appropriate input Low.

The internal circuit is composed of three stages, including a buffer output which provides high noise immunity and stable output. The inputs tolerate voltages up to 7.0 V, allowing the interface of 5.0 V systems to 3.0 V systems.

Features

- High Speed: f_{max} = 170MHz (Typ) at V_{CC} = 5V
- Low Power Dissipation: I_{CC} = 2μA (Max) at T_A = 25°C
- High Noise Immunity: V_{NIH} = V_{NIL} = 28% V_{CC}
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Designed for 2.0 V to 5.5 V Operating Range
- Low Noise: V_{OLP} = 0.8 V (Max)
- Pin and Function Compatible with Other Standard Logic Families
- Latchup Performance Exceeds 300 mA
- ESD Performance:
        Human Body Model > 2000 V;
        Machine Model > 200 V
- Chip Complexity: 128 FETs or 32 Equivalent Gates
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q100 Qualified and PPAP Capable
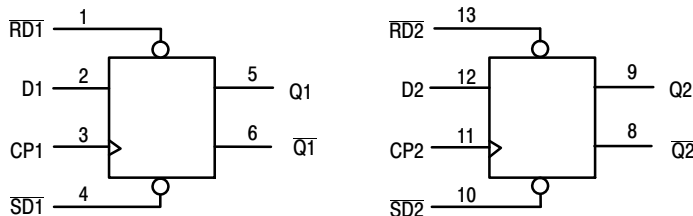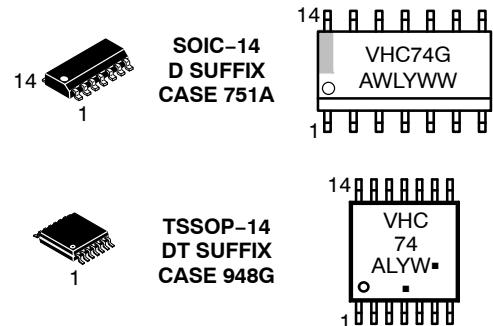- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

Figure 1. LOGIC DIAGRAM

ON Semiconductor®

MARKING DIAGRAMS

SOIC−14
D SUFFIX
CASE 751A

VHC74G
AWLYWW

TSSOP−14
DT SUFFIX
CASE 948G

VHC
74
ALYW∎

A = Assembly Location
WL, L = Wafer Lot
Y, YY = Year
WW, W = Work Week
G or ∎ = Pb−Free Package
(Note: Microdot may be in either location)

FUNCTION TABLE

Inputs				Outputs	
$\overline{SD}$	$\overline{RD}$	CP	D	Q	$\overline{Q}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H*	H*
H	H	⌐	H	H	L
H	H	⌐	L	L	H
H	H	L	X	No Change	
H	H	H	X	No Change	
H	H	⌐	X	No Change	

*Both outputs will remain high as long as Set and Reset are low, but the output states are unpredictable if Set and Reset go high simultaneously.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.
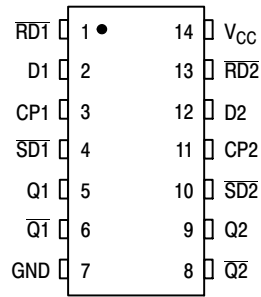
MC74VHC74

```
       ___
       RD1 ⌷ 1 •      14 ⌷ V_CC
        D1 ⌷ 2        13 ⌷ RD2
       CP1 ⌷ 3        12 ⌷ D2
       ___
       SD1 ⌷ 4        11 ⌷ CP2
                           ___
        Q1 ⌷ 5        10 ⌷ SD2
        __
        Q1 ⌷ 6         9 ⌷ Q2
                           __
       GND ⌷ 7         8 ⌷ Q2
```

Figure 2. PIN ASSIGNMENT

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage	− 0.5 to + 7.0	V
V_{in}	DC Input Voltage	− 0.5 to + 7.0	V
V_{out}	DC Output Voltage	− 0.5 to V_{CC} + 0.5	V
I_{IK}	Input Diode Current	−20	mA
I_{OK}	Output Diode Current	±20	mA
I_{out}	DC Output Current, per Pin	±25	mA
I_{CC}	DC Supply Current, V_{CC} and GND Pins	±50	mA
P_D	Power Dissipation in Still Air, SOIC Packages† TSSOP Package†	500 450	mW
T_{stg}	Storage Temperature	−65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
†Derating   SOIC Packages: − 7 mW/°C from 65° to 125°C
                TSSOP Package: − 6.1 mW/°C from 65° to 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high−impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND ≤ (V_{in} or V_{out}) ≤ V_{CC}.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{CC}	DC Supply Voltage	2.0	5.5	V
V_{in}	DC Input Voltage	0	5.5	V
V_{out}	DC Output Voltage	0	V_{CC}	V
T_A	Operating Temperature, All Package Types	−55	+ 125	°C
t_r, t_f	Input Rise and Fall Time V_{CC} = 3.3V ±0.3V V_{CC} =5.0V ±0.5V	0 0	100 20	ns/V

MC74VHC74

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	V_{CC} V	$T_A = 25°C$ Min	Typ	Max	$T_A = -55°C$ to $+125°C$ Min	Max	Unit
V_{IH}	Minimum High–Level Input Voltage		2.0 3.0 to 5.5	1.50 V_{CC} x 0.7			1.50 V_{CC} x 0.7		V
V_{IL}	Maximum Low–Level Input Voltage		2.0 3.0 to 5.5			0.50 V_{CC} x 0.3		0.50 V_{CC} x 0.3	V
V_{OH}	Minimum High–Level Output Voltage	$V_{in} = V_{IH}$ or V_{IL} $I_{OH} = -50\mu A$	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5		1.9 2.9 4.4		V
		$V_{in} = V_{IH}$ or V_{IL} $I_{OH} = -4mA$ $I_{OH} = -8mA$	3.0 4.5	2.58 3.94			2.48 3.80		
V_{OL}	Maximum Low–Level Output Voltage	$V_{in} = V_{IH}$ or V_{IL} $I_{OL} = 50\mu A$	2.0 3.0 4.5		0.0 0.0 0.0	0.1 0.1 0.1		0.1 0.1 0.1	V
		$V_{in} = V_{IH}$ or V_{IL} $I_{OL} = 4mA$ $I_{OL} = 8mA$	3.0 4.5			0.36 0.36		0.44 0.44	
I_{in}	Maximum Input Leakage Current	$V_{in} = 5.5V$ or GND	0 to 5.5			± 0.1		± 1.0	μA
I_{CC}	Maximum Quiescent Supply Current	$V_{in} = V_{CC}$ or GND	5.5			2.0		20.0	μA

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0ns$)

Symbol	Parameter	Test Conditions		$T_A = 25°C$ Min	Typ	Max	$T_A = -55°C$ to $+125°C$ Min	Max	Unit
t_{PLH}, t_{PHL}	Maximum Propagation Delay, CP to Q or $\overline{Q}$	$V_{CC} = 3.3 \pm 0.3V$	$C_L = 15pF$ $C_L = 50pF$		6.7 9.2	11.9 15.4	1.0 1.0	14.0 17.5	ns
		$V_{CC} = 5.0 \pm 0.5V$	$C_L = 15pF$ $C_L = 50pF$		4.6 6.1	7.3 9.3	1.0 1.0	8.5 10.5	
t_{PLH}, t_{PHL}	Maximum Propagation Delay, $\overline{SD}$ or $\overline{RD}$ to Q or $\overline{Q}$	$V_{CC} = 3.3 \pm 0.3V$	$C_L = 15pF$ $C_L = 50pF$		7.6 10.1	12.3 15.8	1.0 1.0	14.5 18.0	ns
		$V_{CC} = 5.0 \pm 0.5V$	$C_L = 15pF$ $C_L = 50pF$		4.8 6.3	7.7 9.7	1.0 1.0	9.0 11.0	
f_{max}	Maximum Clock Frequency (50% Duty Cycle)	$V_{CC} = 3.3 \pm 0.3V$	$C_L = 15pF$ $C_L = 50pF$	80 50	125 75		70 45		MHz
		$V_{CC} = 5.0 \pm 0.5V$	$C_L = 15pF$ $C_L = 50pF$	130 90	170 115		110 75		
C_{in}	Maximum Input Capacitance				4	10		10	pF

		Typical @ 25°C, V_{CC} = 5.0V	
C_{PD}	Power Dissipation Capacitance (Note 1)	25	pF

1. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}/2$ (per flip–flop). C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

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TIMING REQUIREMENTS (Input $t_r = t_f = 3.0ns$)

Symbol	Parameter	V_{CC} V	Guaranteed Limit		Unit
			$T_A = 25°C$	$T_A = -55°C$ to $+125°C$	
t_w	Minimum Pulse Width, CP	3.3 ± 0.3 5.0 ± 0.5	6.0 5.0	7.0 5.0	ns
t_w	Minimum Pulse Width, $\overline{RD}$ or $\overline{SD}$	3.3 ± 0.3 5.0 ± 0.5	6.0 5.0	7.0 5.0	ns
t_{su}	Minimum Setup Time, D to CP	3.3 ± 0.3 5.0 ± 0.5	6.0 5.0	7.0 5.0	ns
t_h	Minimum Hold Time, D to CP	3.3 ± 0.3 5.0 ± 0.5	0.5 0.5	0.5 0.5	ns
t_{rec}	Minimum Recovery Time, $\overline{SD}$ or $\overline{RD}$ to CP	3.3 ± 0.3 5.0 ± 0.5	5.0 3.0	5.0 3.0	ns

ORDERING INFORMATION

Device	Package	Shipping†
MC74VHC74DR2G	SOIC−14 (Pb−Free)	2500 / Tape & Reel
MC74VHC74DTG	TSSOP−14 (Pb−Free)	96 Units / Rail
MC74VHC74DTR2G	TSSOP−14 (Pb−Free)	2500 / Tape & Reel
NLV74VHC74DTR2G*	TSSOP−14 (Pb−Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q100 Qualified and PPAP Capable.
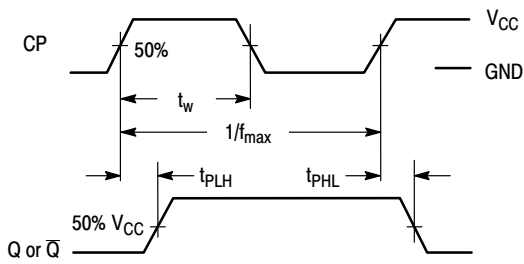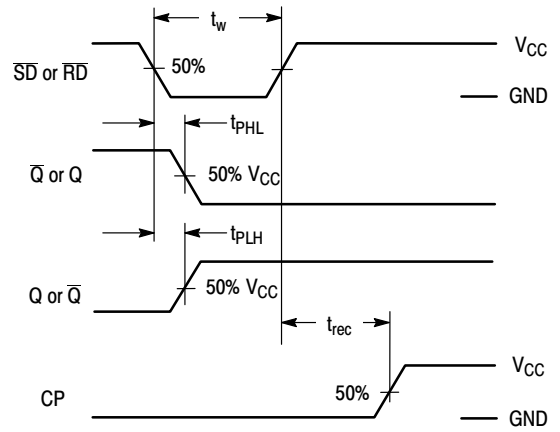
Figure 3.

Figure 4.

Switching Waveforms
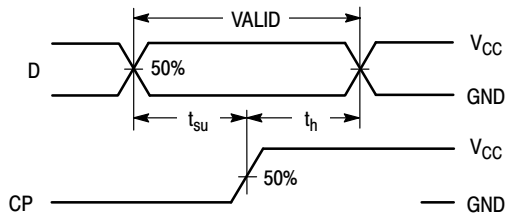
Figure 5.
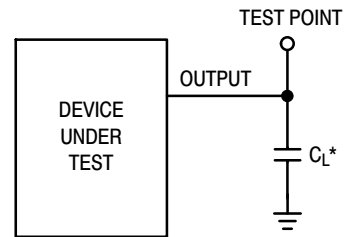
*Includes all probe and jig capacitance

Figure 6.
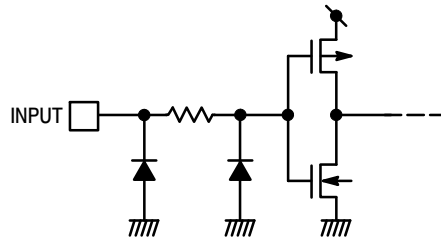
Figure 7. Input Equivalent Circuit

SOIC−14 NB
CASE 751A−03
ISSUE L

DATE 03 FEB 2016

14
1

SCALE 1:1
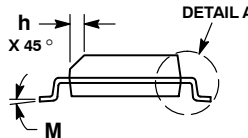
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0 °	7 °	0 °	7 °

DETAIL A

⊕ 0.25 Ⓜ B Ⓜ

13X b

⊕ 0.25 Ⓜ C A Ⓢ B Ⓢ

△ 0.10

C SEATING PLANE

DETAIL A

X 45 °

SOLDERING FOOTPRINT*

6.50

14X 1.18

1.27 PITCH

14X 0.58

DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

14

XXXXXXXXXG
AWLYWW

1

XXXXX = Specific Device Code
A   = Assembly Location
WL   = Wafer Lot
Y   = Year
WW   = Work Week
G   = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

SOIC−14
CASE 751A−03
ISSUE L

DATE 03 FEB 2016

STYLE 1:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. NO CONNECTION
5. ANODE/CATHODE
6. NO CONNECTION
7. ANODE/CATHODE
8. ANODE/CATHODE
9. ANODE/CATHODE
10. NO CONNECTION
11. ANODE/CATHODE
12. ANODE/CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 2:
CANCELLED

STYLE 3:
PIN 1. NO CONNECTION
2. ANODE
3. ANODE
4. NO CONNECTION
5. ANODE
6. NO CONNECTION
7. ANODE
8. ANODE
9. ANODE
10. NO CONNECTION
11. ANODE
12. ANODE
13. NO CONNECTION
14. COMMON CATHODE

STYLE 4:
PIN 1. NO CONNECTION
2. CATHODE
3. CATHODE
4. NO CONNECTION
5. CATHODE
6. NO CONNECTION
7. CATHODE
8. CATHODE
9. CATHODE
10. NO CONNECTION
11. CATHODE
12. CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 5:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. ANODE/CATHODE
5. ANODE/CATHODE
6. NO CONNECTION
7. COMMON ANODE
8. COMMON CATHODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. ANODE/CATHODE
12. ANODE/CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 6:
PIN 1. CATHODE
2. CATHODE
3. CATHODE
4. CATHODE
5. CATHODE
6. CATHODE
7. CATHODE
8. ANODE
9. ANODE
10. ANODE
11. ANODE
12. ANODE
13. ANODE
14. ANODE

STYLE 7:
PIN 1. ANODE/CATHODE
2. COMMON ANODE
3. COMMON CATHODE
4. ANODE/CATHODE
5. ANODE/CATHODE
6. ANODE/CATHODE
7. ANODE/CATHODE
8. ANODE/CATHODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. COMMON CATHODE
12. COMMON ANODE
13. ANODE/CATHODE
14. ANODE/CATHODE

STYLE 8:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. NO CONNECTION
5. ANODE/CATHODE
6. ANODE/CATHODE
7. COMMON ANODE
8. COMMON ANODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. NO CONNECTION
12. ANODE/CATHODE
13. ANODE/CATHODE
14. COMMON CATHODE

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